

## Refine Search

### Search Results -

| Terms          | Documents |
|----------------|-----------|
| L3 and current | 7         |

10/773,198

**Database:**

|   |
|---|
| US Pre-Grant Publication Full-Text Database |
| US Patents Full-Text Database               |
| US OCR Full-Text Database                   |
| EPO Abstracts Database                      |
| JPO Abstracts Database                      |
| Derwent World Patents Index                 |
| IBM Technical Disclosure Bulletins          |

**Search:**

**Refine Search**

Recall Text



Clear

Interrupt

### Search History

**DATE:** Friday, September 17, 2004    [Printable Copy](#)    [Create Case](#)

**Set Name Query**  
side by side

**Hit Count Set Name**  
result set

*DB=USPT; PLUR=YES; OP=ADJ*

|           |                       |     |           |
|-----------|-----------------------|-----|-----------|
| <u>L4</u> | L3 and current        | 7   | <u>L4</u> |
| <u>L3</u> | L2 and electroplating | 12  | <u>L3</u> |
| <u>L2</u> | L1 and interlayer     | 98  | <u>L2</u> |
| <u>L1</u> | wiring adj trench     | 194 | <u>L1</u> |

END OF SEARCH HISTORY

## Hit List

|               |                     |       |          |           |
|---------------|---------------------|-------|----------|-----------|
| Clear         | Generate Collection | Print | Fwd Refs | Bkwd Refs |
| Generate OACS |                     |       |          |           |

### Search Results - Record(s) 1 through 7 of 7 returned.

☐ 1. Document ID: US 6790774 B2

L4: Entry 1 of 7

File: USPT

Sep 14, 2004

US-PAT-NO: 6790774

DOCUMENT-IDENTIFIER: US 6790774 B2

TITLE: Method of forming a wiring film by applying high temperature/high pressure

| Full | Title | Citation | Front | Review | Classification | Date | Reference | Claims | KWIC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|--------|
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|--------|

☐ 2. Document ID: US 6787293 B2

L4: Entry 2 of 7

File: USPT

Sep 7, 2004

US-PAT-NO: 6787293

DOCUMENT-IDENTIFIER: US 6787293 B2

TITLE: Photoresist residue remover composition

| Full | Title | Citation | Front | Review | Classification | Date | Reference | Claims | KWIC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|--------|
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|--------|

☐ 3. Document ID: US 6767826 B2

L4: Entry 3 of 7

File: USPT

Jul 27, 2004

US-PAT-NO: 6767826

DOCUMENT-IDENTIFIER: US 6767826 B2

TITLE: Method of manufacturing semiconductor device

| Full | Title | Citation | Front | Review | Classification | Date | Reference | Claims | KWIC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|--------|
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|--------|

☐ 4. Document ID: US 6724653 B1

L4: Entry 4 of 7

File: USPT

Apr 20, 2004

US-PAT-NO: 6724653

DOCUMENT-IDENTIFIER: US 6724653 B1

TITLE: Magnetic random access memory

| Full | Title | Citation | Front | Review | Classification | Date | Reference |  |  | Claims | KMC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|

☐ 5. Document ID: US 6417575 B2

L4: Entry 5 of 7

File: USPT

Jul 9, 2002

US-PAT-NO: 6417575

DOCUMENT-IDENTIFIER: US 6417575 B2

TITLE: Semiconductor device and fabrication process therefor

| Full | Title | Citation | Front | Review | Classification | Date | Reference |  |  | Claims | KMC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|

☐ 6. Document ID: US 6417094 B1

L4: Entry 6 of 7

File: USPT

Jul 9, 2002

US-PAT-NO: 6417094

DOCUMENT-IDENTIFIER: US 6417094 B1

TITLE: Dual-damascene interconnect structures and methods of fabricating same

| Full | Title | Citation | Front | Review | Classification | Date | Reference |  |  | Claims | KMC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|

☐ 7. Document ID: US 6245676 B1

L4: Entry 7 of 7

File: USPT

Jun 12, 2001

US-PAT-NO: 6245676

DOCUMENT-IDENTIFIER: US 6245676 B1

TITLE: Method of electroplating copper interconnects

| Full | Title | Citation | Front | Review | Classification | Date | Reference |  |  | Claims | KMC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|--------|

|       |                     |       |          |           |               |
|-------|---------------------|-------|----------|-----------|---------------|
| Clear | Generate Collection | Print | Fwd Refs | Bkwd Refs | Generate OACS |
|-------|---------------------|-------|----------|-----------|---------------|

|                |           |
|----------------|-----------|
| Terms          | Documents |
| L3 and current | 7         |

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